L Number	Hits	Search Text	DB	Time stamp
9	3	electrodeposition adj frame	USPAT;	2002/05/14 14:15
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
10	87107	frame with (elements or chip)	USPAT;	2002/05/14 14:18
		•	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
11	17010	(Survey with (alaments on abin)) and	IBM_TDB USPAT;	2002/05/14 14:20
11	17912	(frame with (elements or chip)) and (encapsulant or resin or sealing)	US-PGPUB;	2002/03/14 14:20
		(encapsulant of resin of sealing)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
12	8464	((frame with (elements or chip)) and	USPAT;	2002/05/14 14:23
	0.01	(encapsulant or resin or sealing)) and	US-PGPUB;	
		(cut or remove or removal or cutting)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
13	1265	((frame with (elements or chip)) and	USPAT;	2002/05/14 14:48
		(encapsulant or resin or sealing)) and	US-PGPUB;	
		((cut or remove or removal or cutting)	EPO; JPO;	
		with (metal or substrate))	DERWENT;	
			IBM_TDB	
14	1	("6278177").PN.	USPAT	2002/05/14 15:43
15	148	438/464.ccls. and (resin or sealing or	USPAT;	2002/05/14 15:52
		encapsulant)	US-PGPUB;	
j l		,	EPO; JPO;	
			DERWENT;	
1.0	500	420/106l- and (wasin an applian an	IBM_TDB USPAT;	2002/05/14 15:53
16	520	, ,	US-PGPUB;	2002/03/14 13:33
		encapsulant)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
17	62	438/617.ccls. and (resin or sealing or	USPAT;	2002/05/14 15:56
1 '	02	encapsulant)	US-PGPUB;	2002, 00, 21 20.00
		onoups distance,	EPO; JPO;	
			DERWENT;	
			IBM TDB	
18	173	438/112.ccls. and (resin or sealing or	USPAT;	2002/05/14 15:57
		encapsulant)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	2002/05/14 15 52
19	324	438/124.ccls. and (resin or sealing or	USPAT;	2002/05/14 15:58
		encapsulant)	US-PGPUB;	-
			EPO; JPO;	
			DERWENT; IBM TDB	
20	435	438/127.ccls. and (resin or sealing, or	USPAT;	2002/05/14 15:58
20	435	encapsulant)	US-PGPUB;	2002/00/14 15:50
		Gircapourante,	EPO; JPO;	
			DERWENT;	
			IBM TDB	
21	299	438/107.ccls. and (resin or sealing or	USPAT;	2002/05/14 15:58
		encapsulant)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
22	96	1	USPAT;	2002/05/14 16:04
		encapsulant)	US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	
			IBM_TDB	

Search History 5/14/02 4:14:24 PM Page 1

	203	438/113.ccls. and (resin or sealing or	USPAT;	2002/05/14 16:05
23	203	encapsulant)	US-PGPUB;	
		encapsulane,	EPO; JPO;	
	ļ		DERWENT;	
İ			IBM_TDB	2002/05/14 16:05
24	153	438/121.ccls. and (resin or sealing or	OBLILLY	2002/03/14 16:03
"		encapsulant)	US-PGPUB; EPO; JPO;	ļ
			DERWENT;	
			IBM TDB	ĺ
		438/123.ccls. and (resin or sealing or		2002/05/14 16:05
25	422	encapsulant)	US-PGPUB;	
		encapsulancy	EPO; JPO;	
			DERWENT;	
			IBM_TDB	2222425414 16 26
26	324	438/124.ccls. and (resin or sealing or	USPAT;	2002/05/14 16:06
20		encapsulant)	US-PGPUB;	
			EPO; JPO; DERWENT;	i
		,	IBM TDB	
		l description goaling or	USPAT;	2002/05/14 16:11
27	52		US-PGPUB;	
		encapsulant)	EPO; JPO;	
			DERWENT;	
	ļ		IBM_TDB	
28	74	438/459.ccls. and (resin or sealing or	USPAT;	2002/05/14 16:13
20	'-	encapsulant)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB USPAT;	2002/05/14 16:13
29	148		US-PGPUB;	2002/03/11 19:11
		encapsulant)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
	423	257/784.ccls. and (resin or sealing or	USPAT;	2002/05/14 16:14
30	423	encapsulant)	US-PGPUB;	
		Chaptarity	EPO; JPO;	
			DERWENT;	
			IBM_TDB USPAT;	2002/05/14 16:14
31	2280	257/787.ccls. and (resin or sealing or	USPAT;	2002/03/14 10:14
		encapsulant) '	EPO; JPO;	
			DERWENT;	
			IBM TDB	

Search History 5/14/02 4:14:24 PM Page 2